



Marked-up Claim 7

7. (Twice Amended) A connection structure comprising:

a substrate having a surface and substrate-side pad electrodes formed on the substrate surface;

a surface-mount component having a surface, component-side pad electrodes formed on the surface, and a solder bump formed on the component-side pad, the surface being opposed to the substrate with each component-side pad electrode opposed to one of the substrate-side pad electrodes;

wherein the substrate-side pad electrodes are arranged inside a component-corresponding region, the length of each of the substrate-side pad electrodes being larger than that of the corresponding component-side pad electrode, and wherein each of the component-side pad electrodes is connected to the corresponding substrate-side pad electrode by a solder which has flowed between the component-side pad electrodes and the substrate-side pad electrodes by melting of the solder bump, and the solder bump is arranged so that a center of the solder bump is located off-set from a center of the substrate-side pad.

RECEIVED
OCT 28 2002
TECHNOLOGY CENTER 2800